506058601 05/13/2020

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT6105315

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
KENJI OTA	04/28/2020

RECEIVING PARTY DATA

Name:	DOW TORAY CO., LTD.	
Street Address:	2-24, HIGASHI-SHINAGAWA 2-CHOME	
City:	SHINAGAWA-KU, TOKYO	
State/Country:	JAPAN	
Postal Code:	1408617	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16633441

CORRESPONDENCE DATA

Fax Number: (248)784-5005

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 248-784-5153 Email: patents@wnj.com

Correspondent Name: WARNER NORCROSS + JUDD LLP INTELLECTUAL

Address Line 1: 1500 WARNER BUILDING Address Line 2: 150 OTTAWA AVE NW

Address Line 4: GRAND RAPIDS, MICHIGAN 49503-2487

ATTORNEY DOCKET NUMBER:	157928.189851 (80940)	
NAME OF SUBMITTER:	WYATT J. ISTVAN-MITCHELL	
SIGNATURE:	/Wyatt J. Istvan-Mitchell/	
DATE SIGNED:	05/13/2020	

Total Attachments: 2

source=Assignment#page1.tif source=Assignment#page2.tif

> **PATENT** REEL: 052653 FRAME: 0734 506058601

ASSIGNMENT

For good and valuable consideration, the receipt and adequacy of which is hereby acknowledged, I/we the undersigned owner (assignor),

ASSIGNOR (inventor(s)):

Kenji OTA c/o Dow Toray Co., Ltd. 2-2, Chigusakaigan Ichihara-shi, Chiba 299-0108 JAPAN

a citizen of JAPAN

Hereby sells, assigns and transfers to

ASSIGNEE: Dow Toray Co., Ltd.

2-24, Higashi-Shinagawa 2-chome

Shinagawa-ku, Tokyo 1408617 Japan

and the successors and assigns of the ASSIGNEE, the entire right, title and interest for the United States and its territorial possessions and in all foreign countries, including all rights to claim priority in and to any and all improvements which are disclosed in the invention entitled

THERMALLY-CONDUCTIVE SILICONE GEL COMPOSITION, THERMALLY-CONDUCTIVE MEMBER, AND HEAT DISSIPATION STRUCTURE

and which is found in US Application No. 16/633,441 filed on 23 January 2020 and in PCT Application Serial No. PCT/JP2018/026227 filed on 11 July 2018 which claims priority to Japanese Patent Application No. 2017-142708 filed on 24 July 2017, and any legal equivalent thereof in a foreign country, including the right to claim priority, and, in and to, all Letters Patent to be obtained for said invention or arising from or claiming priority to any of the above identified patent applications, or any national filing, continuation, division, renewal, or substitute thereof arising from or claiming priority to any of the above identified patent applications, and as to letters patent any re-issue or re-examination thereof.

To comply with 37 C.F.R. § 3.21 for recordal of this assignment, I, an ASSIGNOR signing below, hereby authorize and request Warner Norcross + Judd LLP to insert the filing dates and serial numbers of the above identified patent applications when they become known in the space above if not already provided.

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and ASSIGNOR will testify as to the same in any interference, litigation or proceeding related thereto.

ASSIGNMENT

ASSIGNOR further covenants to promptly execute and deliver to ASSIGNEE or its successors or assigns any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof and to execute any divisional or continuing application or applications which may be necessary or proper to obtain full protection on the invention hereby assigned; and to execute any and all supplemental oaths and preliminary statements, should the same be necessary or desirable in the prosecution of the aforesaid applications and to carry out the purposes thereof.

This is to certify that Kenji OTA has signed this document in my presence this

28th day of April, 2020.

Signature of Witness